

L Number	Hits	Search Text	DB	Time stamp
1	3	"06171089"	JPO; DERWENT	2003/11/24 14:47
2	1	1994-238262.NRAN.	DERWENT	2003/11/24 14:45
3	0	6171089.URPN.	USPAT	2003/11/24 14:46
4	0	6171089.URPN.	USPAT	2003/11/24 14:46
5	1	1997-121178.NRAN.	DERWENT	2003/11/24 14:46
6	10	((("5902492") or ("4638328") or ("4601777") or ("5870123") or ("6375858"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/24 14:48
-	382	(216/27).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:03
-	628	(29/890.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 18:58
-	690	(347/20).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:10
-	630	(347/29).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 18:59
-	738	(347/40).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:00
-	502	(347/44).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:01
-	1281	(347/47).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:01
-	363	(347/49).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:01
-	779	(347/65).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:02
-	183	(347/67).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:02
-	156	(347/69).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:02
-	524	(347/71).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 19:02

-	269	((216/27).CCLS.) and nozzle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:03
-	257	((216/27).CCLS.) and nozzle and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:03
-	4653	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)) and nozzle and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:11
-	2226	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)) and nozzle and etch\$3 and mask\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:06
-	2518	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)).ti. and nozzle and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:07
-	606	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)).ti. and nozzle and etch\$3 and ((silicon adj dioxide) or SiO2 or "SiO.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:09
-	772	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)).ti. and nozzle and etch\$3 and ("<110>" or "{110}")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:09
-	688	(347/54).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:10
-	3105	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)) and nozzle and etch\$3 and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:11
-	1124	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)) and (nozzle adj plate) and etch\$3 and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:12
-	274	(inkjet or (ink adj jet) or ink-jet or ((liquid or thermal) adj \$5head)) and (nozzle adj plate).ab. and etch\$3 and silicon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/21 19:12